ADD: Room 598, 5th Floor, Building 101, Shangbu Industrial Zone, Huaqiang North Street, Futian District, Shenzhen

CUSTOMER:

# **SPECIFICATIONS**

|                   | DESCRIPTION: Ceramic Antenna     |                                  |         |                 |                             |   |            |
|-------------------|----------------------------------|----------------------------------|---------|-----------------|-----------------------------|---|------------|
|                   | CUSTOMER F                       | PART NO:                         |         |                 |                             |   |            |
|                   | OUR MODEL                        | NO:                              | PI      | BX1608MA        | 02                          |   |            |
|                   | DATE:                            |                                  |         |                 |                             |   |            |
|                   |                                  |                                  |         |                 |                             |   |            |
|                   | PLEASE RET                       | TURN TO US                       | ONE CO  | PY OF "SPEC]    | IFICATIO                    | ON FOR APPROVA  | L <b>"</b> |
|                   | WITH YOUR                        | APPROVED                         | SIGNATU | RES             |                             |   |            |
|                   |                                  |                                  |         |                 |                             |   |            |
|                   |                                  |                                  |         |                 |                             |   |            |
|                   | Check                            |                                  | audit   | Liu Fei         | make                        | Liu xiaomei   |            |
|                   | Si                               | ignature                         |         |                 |                             |   |            |
|                   |                                  | Date                             |         |                 |                             |   |            |
| $x=\pm$           | S OTHER SPEC<br>X.X=±<br>.ES = ± | IFIED TOLERA<br>X.XX=<br>HOLEDIA |         | PENGBANXING     |                             | nen Pengbian Ind<br>blogy Co., LTD                                      | lustrial   |
| SCALE:<br>DRAWN I |                                  | UNIT: mm CHECKED B APPROVED      | BY: XD  | TECHNOLOGY Lin  | nited AND SHA<br>THE MANUFA | CATIONS ARE THE PROPER<br>LLL NOT BE REPRODUCED<br>CTURE OR SALE OF APP | OR USED AS |
|                   | CHIP2450-1608                    |                                  |         | DOCUMENT<br>NO. |                             | 1608  | SPEC REV.  |
|                   |                                  |                                  |         |                 |                             |   |            |

### **PBX1608MA02 Specification**

Operating Temp. : -40 ℃~+85 ℃

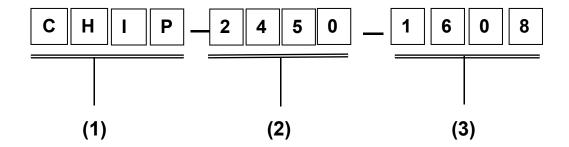
#### 1. FEATURES:

- Light weight, compact
- Wide bandwidth, low cost
- Built-in antenna with high gain

#### 2. APPLICATIONS:

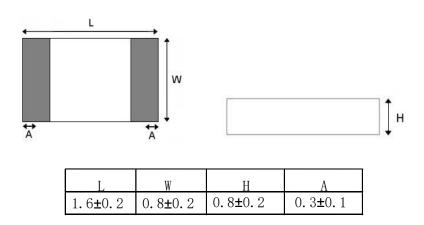
- Bluetooth, Wireless LAN, Mobile TV
- Home RF System, etc

#### 3. PRODUCT IDENTIFICATION

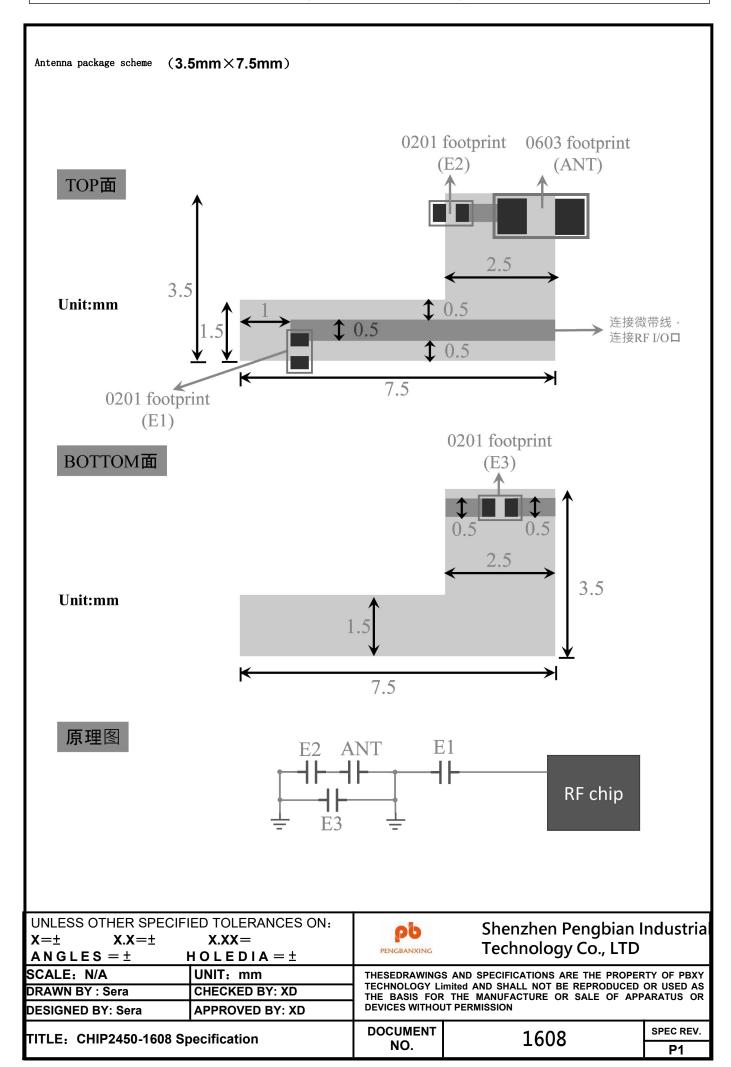


- (1) Product type: Multilayer chip Antenna
- (2) Center Frequency: 2450MHz
- (3) External Dimensions (L×W) (mm): 1.6\*0.8

#### 4. SHAPE AND DIMENSIONS:



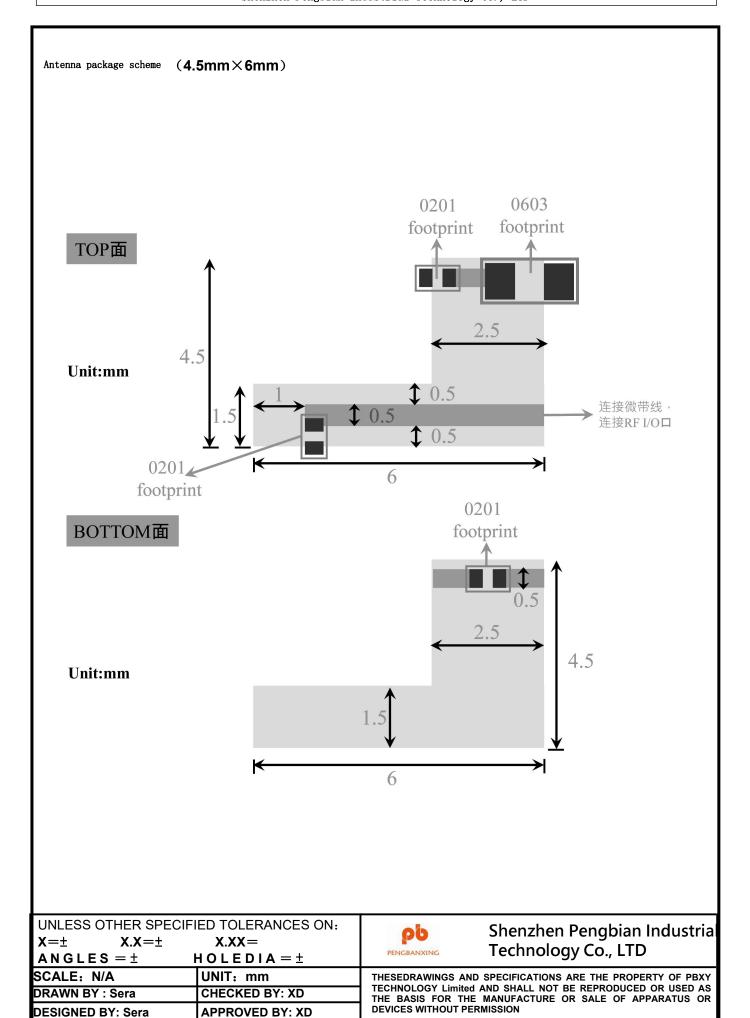
| UNLESS OTHER SPECIF<br>X=± X.X=±<br>ANGLES = ± | IED TOLERANCES ON:  X.XX= HOLEDIA = ± | PENGBANXING   | Shenzhen Pengbian Ind<br>Technology Co., LTD | dustrial  |
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| DESIGNED BY: Sera                              | APPROVED BY: XD                       | DEVICES WITHOU  | JT PERMISSION                                | _         |
| TITLE: CHIP2450-1608 S                         | necification                          | 1608  |  | SPEC REV. |
| 111122: 01111 2400-1000 0                      | secification                          | NO.   | 1000   | P1        |



SPEC REV.

P1

1608



**DOCUMENT** 

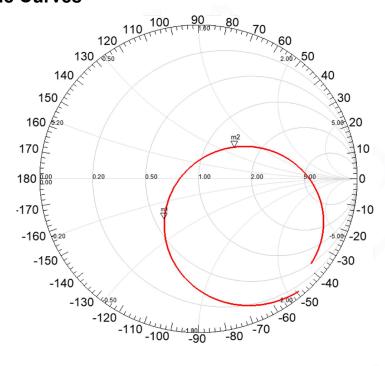
NO.

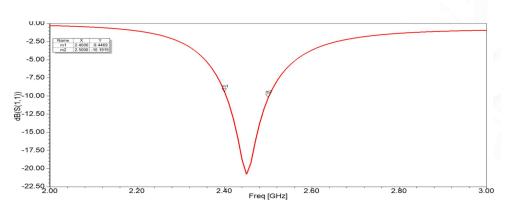
TITLE: CHIP2450-1608 Specification

## **Electrical Characteristics**

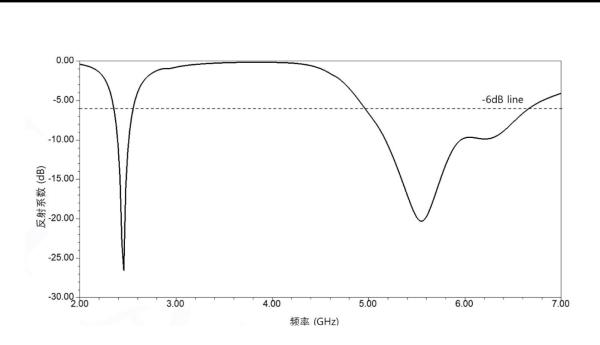
|   | Feature           | Specification   |
|---|-------------------|-----------------|
| 1 | Central frequency | 2.45GHz         |
| 2 | Bandwidth         | >150MHz         |
| 3 | Peak gain         | 2.78 dBi        |
| 4 | VSWR              | <2              |
| 5 | Polarization      | Linear          |
| 6 | Azimuth beamwidth | Omnidirectional |
| 7 | Impedance         | 50 Ω            |

## **Characteristic Curves**

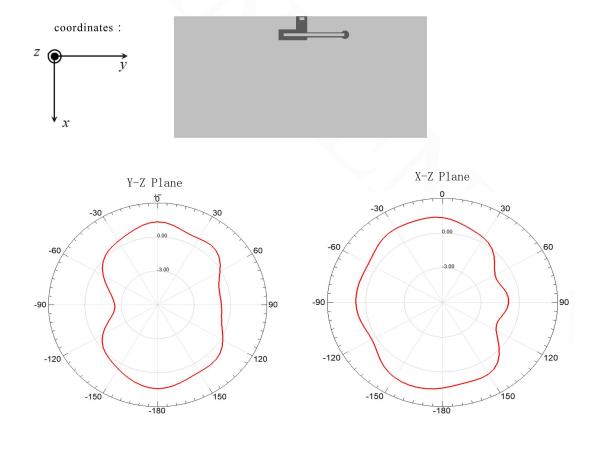




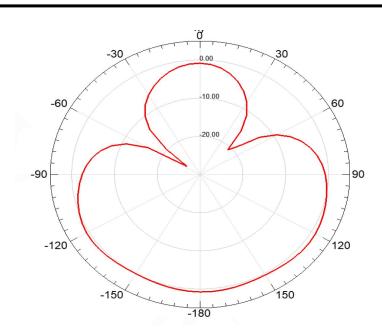
| $X=\pm$ $X.X=\pm$                  | FIED TOLERANCES ON: X.XX= HOLEDIA = ± | PENGBANXING   | Shenzhen Pengbian I<br>Technology Co., LTD | ndustrial |  |
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| TITLE: CHIP2450-1608 Specification |                                       | DOCUMENT  | 1608                                       | SPEC REV. |  |
| 111LL; Offin 2430-1000             | Specification                         | NO. 1000 P1   |  |           |  |



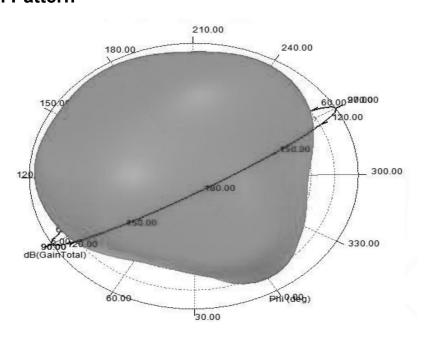
# **Radiation Pattern**



| UNLESS OTHER SPECIF X=± X.X=± ANGLES = ± | IED TOLERANCES ON: X.XX= HOLEDIA=± | PENGBANXING   | Shenzhen Pengbian I<br>Technology Co., LTD | ndustrial |  |
|--|------------------------------------|---|--|-----------|--|
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| DESIGNED BY: Sera                        | APPROVED BY: XD                    | DEVICES WITHOUT PERMISSION  |  |           |  |
| TITLE: CHIP2450-1608 Specification       |                                    | DOCUMENT  | 1608                                       | SPEC REV. |  |
| 1112E; Offin 2430-1000 O                 | Jeonication                        | NO. 1000 P  |  |           |  |



# **3D Radiation Pattern**

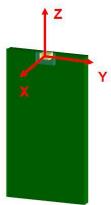


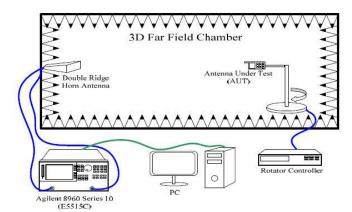
| Frequency  | 2400MHz | 2450MHz | 2500MHz |
|------------|---------|---------|---------|
| Avg. gain  | -1.92   | -1.35   | -1.56   |
| Peak gain  | 1.79    | 2.78    | 2.66    |
| Efficiency | 74.55   | 80.25   | 76.98   |

| UNLESS OTHER SPECII<br>X=± X.X=±<br>ANGLES = ± | FIED TOLERANCES ON:  X.XX=  HOLEDIA = ± | PENGBANXING   | Shenzhen Pengbian I<br>Technology Co., LTD | ndustrial |  |
|--|---|---|--|-----------|--|
| SCALE: N/A                                     | UNIT: mm                                | THESEDRAWINGS AND SPECIFICATIONS ARE THE PROPERTY OF PBXY   |  |           |  |
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| DESIGNED BY: Sera                              | APPROVED BY: XD                         | DEVICES WITHOUT PERMISSION  |  |           |  |
| TITLE: CHIP2450-1608 Specification             |   | DOCUMENT  | 1608                                       | SPEC REV. |  |
| 111LL; OIIII 2430-1000 C                       | pecinication                            | NO. 1008 P1   |  | P1        |  |

#### **Radiation Pattern**

The Gain pattern is measured in FAR-field chamber. DUT is placed on the table of rotator,a standard horn antenna and Vector Network Analyzer is used to collect data.





#### **Environmental Characteristics**

#### (1) Reliability Test

| Item                              | Condition  | Specification   |
|-----------------------------------|--|---|
| Thermal shock                     | 1. $30\pm3$ minutes at $-40^{\circ}$ C $\pm5^{\circ}$ C,<br>2. Convert to $+105^{\circ}$ C (5 minutes)<br>3. $30\pm3$ minutes at $+105^{\circ}$ C $\pm5^{\circ}$ C,<br>4. Convert to $-40^{\circ}$ C (5 minutes)<br>5. Total 100 continuous cycles | No apparent damage<br>Fulfill the electrical<br>spec. after test. |
| Humidity resistance               | <ol> <li>Humidity: 85% R.H.</li> <li>Temperature: 85±5° C</li> <li>Time: 1000 hours.</li> </ol>  | No apparent damage<br>Fulfill the electrical<br>spec. after test. |
| High<br>temperature<br>resistance | 1. Temperature: 150° C±5° C<br>2. Time: 1000 hours.  | No apparent damage<br>Fulfill the electrical<br>spec. after test. |
| Low temperature resistance        | 1. Temperature: -40° C±5° C<br>2. Time: 1000 hours.  | No apparent damage<br>Fulfill the electrical<br>spec. after test. |
| Soldering heat resistance         | 1. Solder bath temperature : $260\pm5^{\circ}\!$   | No apparent damage  |
| Solderability                     | The dipped surface of the terminal shall be at least 95% covered with solder after dipped in solder bath of $245\pm5^\circ\!$  | No apparent damage  |

#### (2) Storage Condition

#### (a) At warehouse:

The temperature should be within  $0 \sim 30^{\circ}\text{C}$  and humidity should be less than 60% RH. The product should be used within 1 year from the time of delivery.

#### (b) On board:

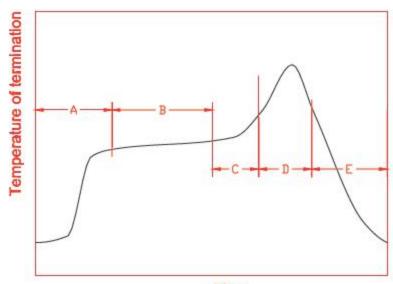
The temperature should be within -40~85°C and humidity should be less than 85% RH.

#### (3) Operating Temperature Range

Operating temperature range :  $-40^{\circ}$ C to  $+105^{\circ}$ C.

| UNLESS OTHER SPECI<br>X=± X.X=±<br>ANGLES = ± | FIED TOLERANCES ON:  X.XX=  HOLEDIA = ± | PENGBANXING   | Shenzhen Pengbian I<br>Technology Co., LTD | ndustrial |  |
|---|---|---|--|-----------|--|
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| DESIGNED BY: Sera                             | APPROVED BY: XD                         | DEVICES WITHOUT PERMISSION  |  |           |  |
| TITLE: CHIP2450-1608 Specification            |   | DOCUMENT  | 1608                                       | SPEC REV. |  |
| 1111EE: 01111 2430-1000 C                     | ppecification                           | NO.   | 1000 P1                                    |           |  |

# 8. Recommended Reflow Soldering



#### Time

| 1 <sup>st</sup> rising temperature                           | The normal to Preheating temperature                         | 30s to 60s  |
|--|--|---|
| Preheating   | 140°C to 160°C   | 60s to 120s   |
| 2 <sup>nd</sup> rising temperature                           | Preheating to 200°C  | 20s to 40s  |
|  | if 220°C   | 50s~60s   |
| Preheating   | if 230°C   | 40s∼50s   |
| Main heating   | if 240°C   | 30s~40s   |
| 5 C S C S C S C S C S C S C S C S C S C                      | if 250°C   | 20s~40s   |
| Preheating  2 <sup>nd</sup> rising temperature  Main heating | if 260°C   | 20s~40s   |
| Regular cooling  | 200°C to 100°C   | 1°C/s ~ 4°C/s   |
|  | Preheating  2 <sup>nd</sup> rising temperature  Main heating | 1st rising temperature  Preheating  2nd rising temperature  Preheating to 200°C  if 220°C  if 230°C  Main heating  if 240°C  if 250°C  if 260°C |

<sup>\*</sup>reference: J-STD-020C

#### (1) Soldering Gun Procedure

Note the follows, in case of using solder gun for replacement.

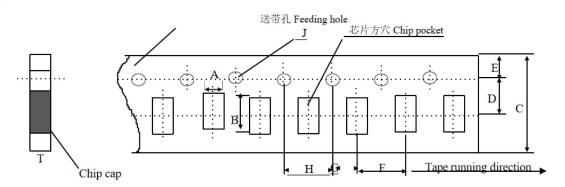
- (a) The tip temperature must be less than  $350^{\circ}\,$  C for the period within 3 seconds by using soldering gun under 30 W.
- (b) The soldering gun tip shall not touch this product directly.

#### (2) Soldering Volume

Note that excess of soldering volume will easily get crack the body of this product.

| UNLESS OTHER SPECI<br>X=± X.X=±<br>ANGLES = ± | FIED TOLERANCES ON:  X.XX=  HOLEDIA = ± | PENGBANXING   | Shenzhen Pengbian I<br>Technology Co., LTD | ndustrial |  |
|---|---|---|--|-----------|--|
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| TITLE: CHIP2450-1608 Specification            |   | DOCUMENT  | 1608                                       | SPEC REV. |  |
| 1111LL; CHIF 2430-1000 (                      | opecinication                           | NO.   | 1008                                       | P1        |  |

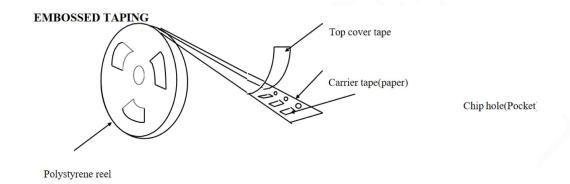
# Dimensions of paper taping:



Unit: mm

| 代号Code<br>纸带规格<br>papersize | A     | В     | С     | D*    | E     | F     | G*    | Н     | J        | T    |
|-----------------------------|-------|-------|-------|-------|-------|-------|-------|-------|----------|------|
| 尺寸                          | 1.10  | 1.90  | 8.00  | 3.50  | 1.75  | 4.00  | 2.00  | 4.00  | 1.50     | 1.10 |
| <u></u>                     | ±0.10 | ±0.10 | ±0.10 | ±0.05 | ±0.10 | ±0.10 | ±0.10 | ±0.10 | -0/+0.10 | Max  |

Reel (4000 pcs/Reel)



# **Storage Period**

The guaranteed period for solderability is 6 months (Under deliver package condition). Temperature:  $5\sim40^{\circ}$ C /Relative Humidity:  $20\sim70\%$ 

| UNLESS OTHER SPECIF<br>X=± X.X=±<br>ANGLES = ± | FIED TOLERANCES ON:  X.XX=  HOLEDIA = ± | PENGBANXING   | Shenzhen Pengbian I<br>Technology Co., LTD |           |
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|  |   |   |  | P1        |